



PATENT ABSTRACTS OF JAPAN

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(54) OPTICAL SEMICONDUCTOR DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide an optical semiconductor device capable of taking a surface mounting step by solder reflow technique posing no problem at all.

SOLUTION: An optical semiconductor device is provided with a resin package, the first and second inner leads 41 and 51 in parallel or almost in parallel with each other to be extended inward from one end of the resin package, a semiconductor chip 3 bonded onto the inner end of the first lead 41, a wire W connecting the inner ends of this semiconductor chip 3 and the second inner lead 51, the first and second outer leads 42 and 52 while a connecting terminal making the surface contact with a substrate is formed on the first and second outer leads 42 and 52. On such a constitution, the resin package is provided with the first translucent resin package part 21 sealing the inner ends of the first and second inner leads 41 and 42, the semiconductor chip 3 and the wire W on the front end side as well as the second heat resistant resin package part 22 on the base end side.

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